MA5J002E

Silicon epitaxial planar type

For high speed switching circuits

■ Features

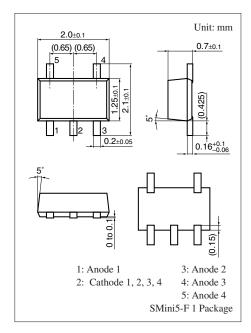
- Includes 4 elements of cathode common connection
- Parts reduction is possible
- Ideal for surge voltage absorption

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	80	V
Maximum peak reverse voltage	V_{RM}	80	V
Forward current *1	I_{F}	100	mA
Peak forward current *1	I_{FM}	225	mA
Non-repetitive peak forward surge current *1, 2	I_{FSM}	500	mA
Junction temperature	T _j	150	°C
Operating ambient temperature	T _{opr}	-25 to +105	°C
Storage temperature	T _{stg}	-55 to +150	°C

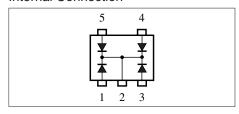
Note) *1: Value in single diode used.

*2: t = 1 s



Marking Symbol: M5B

Internal Connection

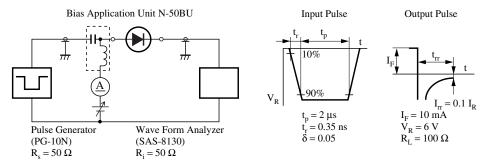


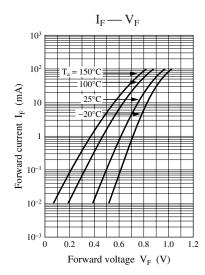
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

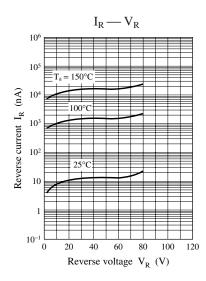
Symbol	Conditions	Min	Тур	Max	Unit
V_F	$I_F = 100 \text{ mA}$			1.2	V
V_R	$I_R = 100 \mu A$	80			V
I_R	$V_R = 75 \text{ V}$			100	nA
C _t	$V_R = 0 V, f = 1 MHz$			2	pF
t _{rr}	$I_F = 10 \text{ mA}, V_R = 6 \text{ V}$ $I_{rr} = 0.1 I_R, R_1 = 100 \Omega$			3	ns
	V_F V_R I_R C_t	V_F $I_F = 100 \text{ mA}$ V_R $I_R = 100 \mu\text{A}$ I_R $V_R = 75 V$ C_t $V_R = 0 V, f = 1 \text{ MHz}$	$\begin{array}{cccc} V_F & I_F = 100 \text{ mA} \\ V_R & I_R = 100 \mu\text{A} & 80 \\ I_R & V_R = 75 V \\ C_t & V_R = 0 V, f = 1 M\text{Hz} \\ t_{rr} & I_F = 10 m\text{A}, V_R = 6 V \end{array}$	$\begin{array}{cccc} V_F & I_F = 100 \text{ mA} & & & & & & & & \\ V_R & I_R = 100 \mu\text{A} & & & & & & & \\ I_R & V_R = 75 V & & & & & \\ C_t & V_R = 0 V, f = 1 MHz & & & & \\ t_{rr} & I_F = 10 m\text{A}, V_R = 6 V & & & & \\ \end{array}$	$\begin{array}{cccccccccccccccccccccccccccccccccccc$

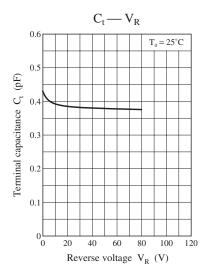
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring method for diodes.

- 2. Absolute frequency of input and output is 100 MHz.
- 3. *: t_{rr} measurement circuit









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